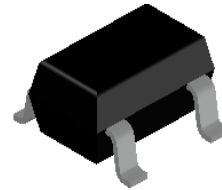


Features

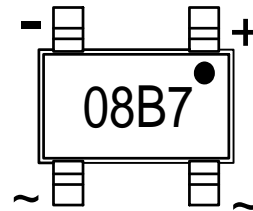
- Low profile space
- Ideal for printed circuit board
- Low reverse leakage
- Applied in power supply equipment
- High ring wave immunity capability
- High temperature soldering guaranteed:
260°C/10 seconds
- Component in accordance to
RoHS 2011/65/EU and WEEE 2002/96/EC



RoHS
COMPLIANT

Mechanical Data

- **Case:** IBS
The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity:** Mark a dot at the positive position
The other end on the same side is negative
AC pole is on the other side
- **Mounting Position:** Any



Major Ratings and Characteristics

$I_{F(AV)}$	0.8A
V_{RRM}	400V to 1000V
I_{FSM}	30A
V_F	1.0V
$T_{Jmax.}$	125°C

Maximum Ratings & Thermal Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Items	Symbol	VMB4S	VMB6S	VMB8S	VMB10S	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	400	600	800	1000	V
Average forward rectified current	$I_{F(AV)}$	0.8				A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	30				A
Rating for fusing ($t < 8.3$ ms)	I^2t	3.7				A ² s
Thermal resistance from junction to ambient	$R_{\theta JA}^{(1)}$	180				°C/W
Thermal resistance from junction to lead	$R_{\theta JL}$	35				
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +125				

Note 1: On 1.6mm thick glass epoxy P.C.B.(1OZ) mounted on 0.05 x 0.05" (1.3 x 1.3 mm) solder pads.

Electrical Characteristics_ (T_A = 25 °C unless otherwise noted)

Items	Test conditions	Symbol	Min.	Typ.	Max.	Unit
Junction temperature	I _F =0.15A, V _{RMS} =220V, T _A =25°C and conduction angle=80°	T _J	-	-	80	°C
Instantaneous forward voltage	I _F =0.8A ⁽²⁾	V _F	-	1.0	1.1	V
Reverse current	V _R =V _{DC}	T _J =25°C	-	-	5.0	μA
		T _J =125°C	-	-	100.0	

Note 2: Pulse test:300μs pulse width,1% duty cycle.

Characteristics Curves

Fig.1 Foward Current Derating Curve

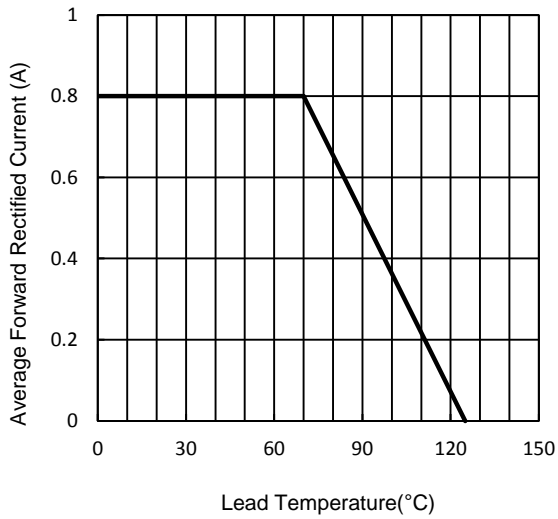
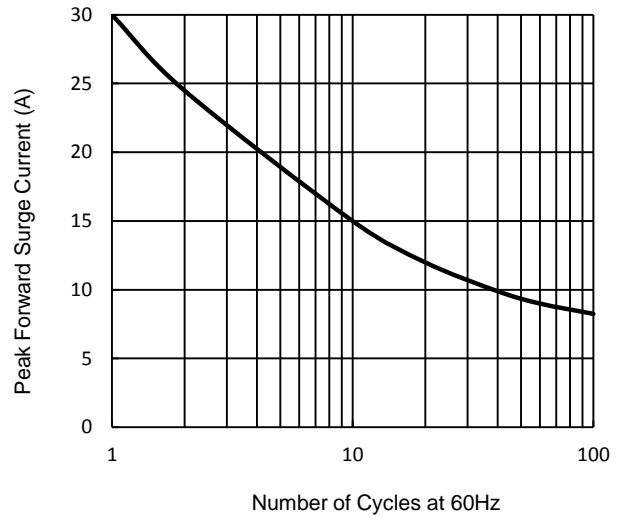


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current



Characteristics Curves

Fig.3 Typical Forward Current Characteristics

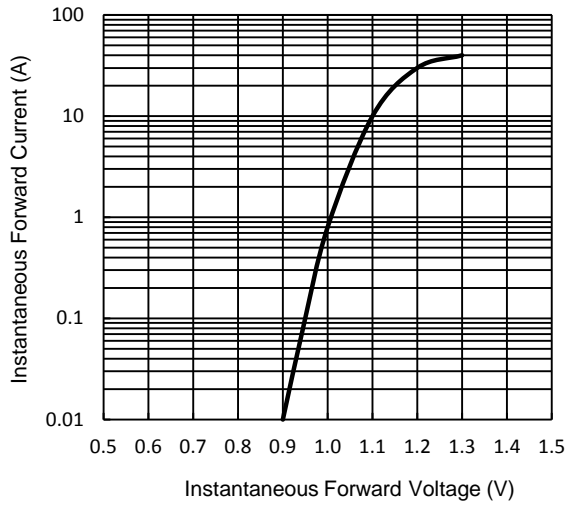


Fig.4 Typical Reverse Characteristics

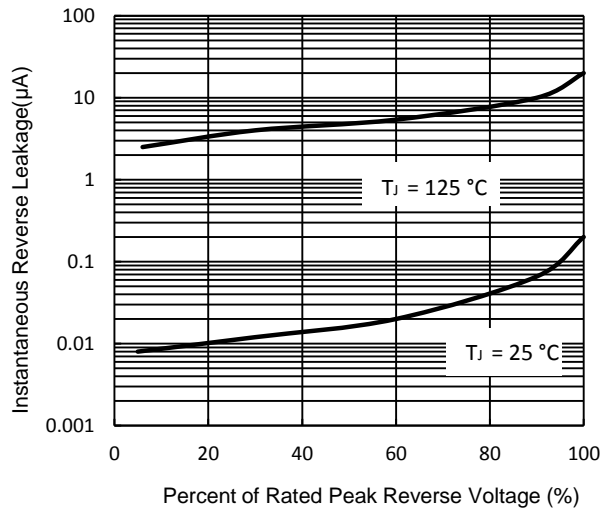
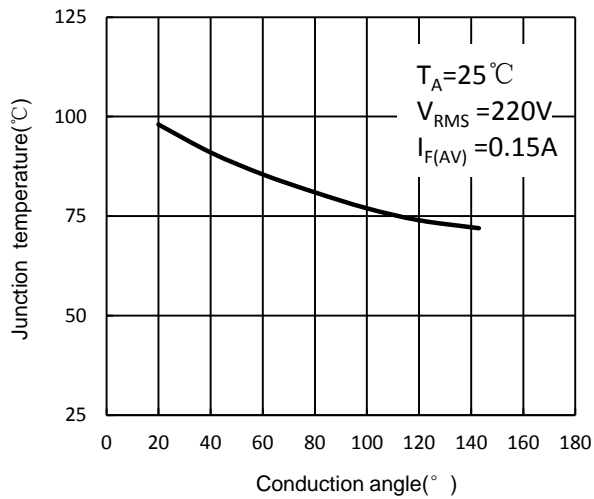
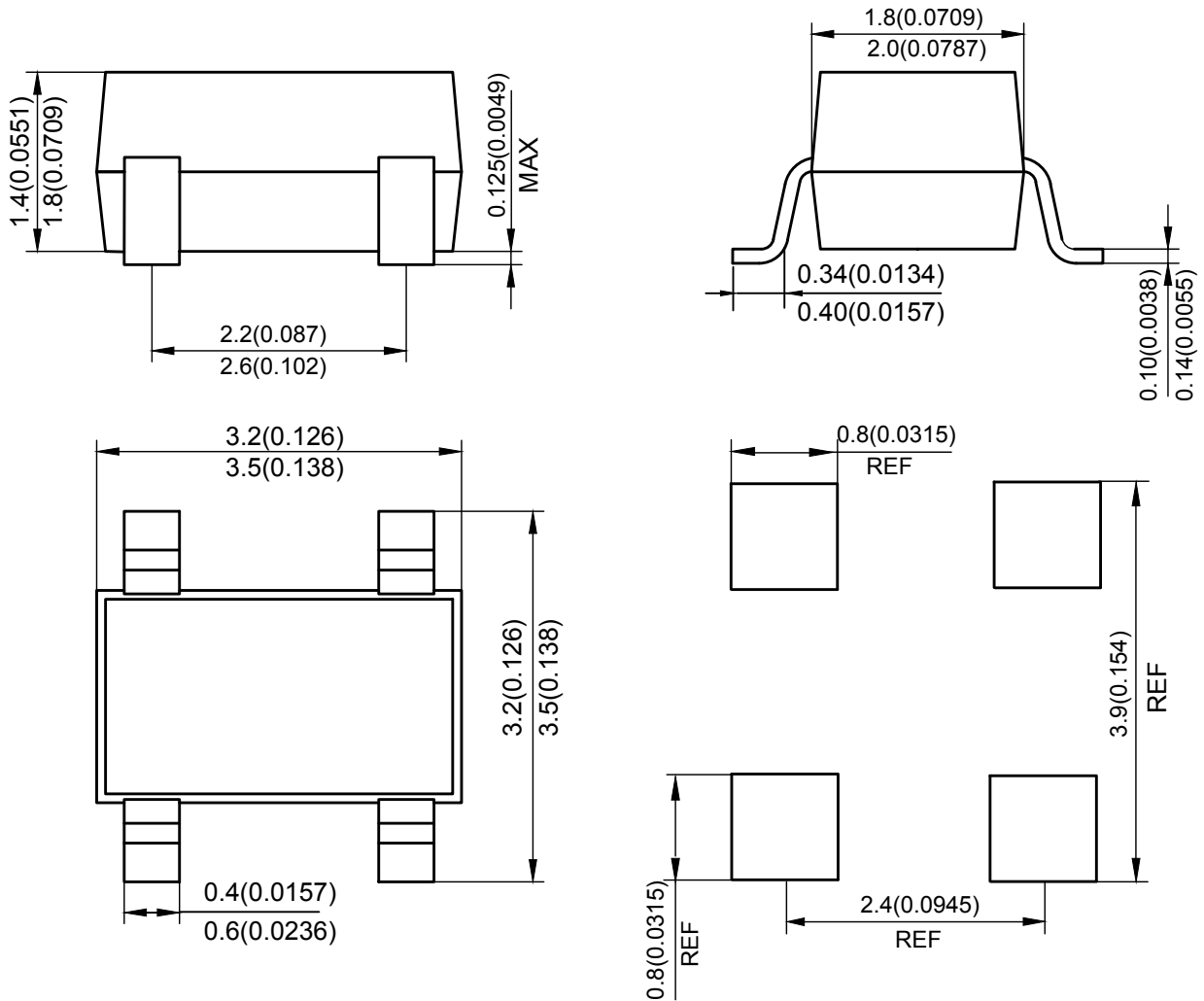


Fig.5 Junction temperature vs. conduction angle



Package Outline

IBS



Dimensions in millimeters(inches)